



Material Content Data Sheet



Sales Product Name				IPD60R600C6		Issued		26. September 2017	
MA#				MA001182894					
Package				PG-TO252-3-313		Weight*		318.75 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.063	0.96	0.96	9609	9609	
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		139		
	non noble metal	iron	7439-89-6	0.147	0.05		462		
	non noble metal	copper	7440-50-8	147.096	46.14	46.20	461478	462079	
	non noble metal	aluminium	7429-90-5	0.513	0.16	0.16	1611	1611	
wire	non noble metal	aluminium	7429-90-5	0.513	0.16	0.16	1611	1611	
encapsulation	organic material	carbon black	1333-86-4	1.407	0.44		4413		
	plastics	epoxy resin	-	24.616	7.72		77226		
	inorganic material	silicondioxide	60676-86-0	114.639	35.97	44.13	359653	441292	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11733	11733	
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11		
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4457	4468	
solder	non noble metal	tin	7440-31-5	0.057	0.02		179		
	noble metal	silver	7440-22-4	0.071	0.02		224		
	non noble metal	lead	7439-92-1	2.729	0.86	0.90	8562	8965	
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	iron	7439-89-6	0.019	0.01		60		
	non noble metal	copper	7440-50-8	19.177	6.02	6.03	60165	60243	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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